6/2827

TRANSMITTAL LETTER (General - Patent Pending)	Docket No. EN9-98-141US2

In Re Application Of: **Sebesta et al.**

Serial No.	Filing Date	Examiner	Group Art Unit
09/526,957	3/16/00	Mitchell, J.	2827

Title: **VARIABLE THICKNESS PADS ON A SUBSTRATE SURFACE**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Amendment

in the above identified application.

- ☑ No additional fee is required.
- ☐ A check in the amount of is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457(IBM)** as described below. A duplicate copy of this sheet is enclosed.
  - ☐ Charge the amount of
  - ☒ Credit any overpayment.
  - ☒ Charge any additional fee required.

Jack P. Friedman
Signature

Dated: **7/1/02**

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I certify that this document and fee is being deposited on 7/1/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Kim Dwileski
Signature of Person Mailing Correspondence

Kim Dwileski
Typed or Printed Name of Person Mailing Correspondence

cc:

#16/C
T. BELL.
7-16-02

DOCKET NO. EN9-98-141US2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Sebesta *et al.*

Examiner: Mitchell, J.

Serial No.: 09/526,957

Art Unit: 2827

Filed: 3/16/00

For: **VARIABLE THICKNESS PADS ON A SUBSTRATE SURFACE**

Commissioner for Patents
Washington D.C. 20231

Sir:

This paper is being filed in response to the Office Action mailed April 10, 2002. Applicants respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

In the Specification

Please insert the following paragraph between lines 9 and 10 on page 12:

In FIG. 3: the first circuit line **30** is shown as on the top surface **18** (see FIG. 1 for top surface **18**) of the substrate **10** and not embedded into the substrate **10**; the second circuit line **32** is shown as on the top surface **18** of the substrate **10** and not embedded into the substrate **10**; and the third circuit line **34** is shown as on the bottom surface **19** (see FIG. 1 for bottom surface **19**) of

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